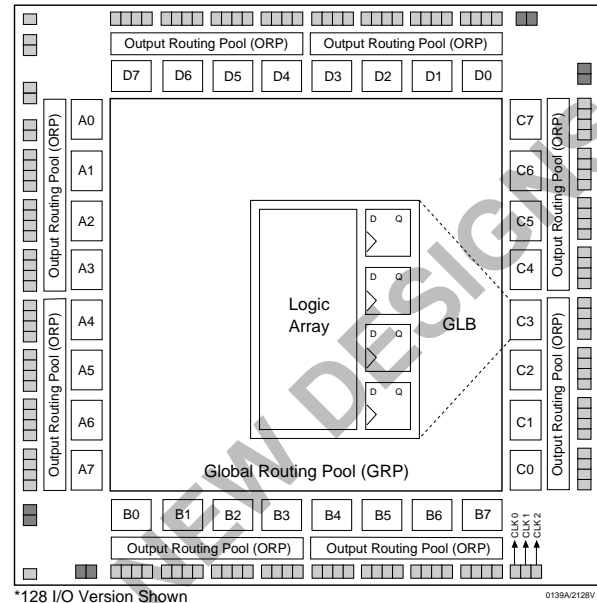


Features

- **HIGH DENSITY PROGRAMMABLE LOGIC**
 - 6000 PLD Gates
 - 128 and 64 I/O Pin Versions, Eight Dedicated Inputs
 - 128 Registers
 - High Speed Global Interconnect
 - Wide Input Gating for Fast Counters, State Machines, Address Decoders, etc.
 - Small Logic Block Size for Random Logic
- **3.3V LOW VOLTAGE 2128 ARCHITECTURE**
 - Interfaces with Standard 5V TTL Devices
 - The 128 I/O Pin Version is Fuse Map Compatible with 5V ispLSI 2128
- **HIGH PERFORMANCE E²CMOS[®] TECHNOLOGY**
 - $f_{max} = 80$ MHz Maximum Operating Frequency
 - $t_{pd} = 10$ ns Propagation Delay
 - Electrically Erasable and Reprogrammable
 - Non-Volatile
 - 100% Tested at Time of Manufacture
 - Unused Product Term Shutdown Saves Power
- **IN-SYSTEM PROGRAMMABLE**
 - 3.3V In-System Programmability (ISP[™]) Using Boundary Scan Test Access Port (TAP)
 - Open-Drain Output Option for Flexible Bus Interface Capability, Allowing Easy Implementation of Wired-OR or Bus Arbitration Logic
 - Increased Manufacturing Yields, Reduced Time-to-Market and Improved Product Quality
 - Reprogram Soldered Devices for Faster Prototyping
- **THE EASE OF USE AND FAST SYSTEM SPEED OF PLDs WITH THE DENSITY AND FLEXIBILITY OF FPGAS**
 - Enhanced Pin Locking Capability
 - Three Dedicated Clock Input Pins
 - Synchronous and Asynchronous Clocks
 - Programmable Output Slew Rate Control
 - Flexible Pin Placement
 - Optimized Global Routing Pool Provides Global Interconnectivity
- **ispDesignEXPERT[™] – LOGIC COMPILER AND COMPLETE ISP DEVICE DESIGN SYSTEMS FROM HDL SYNTHESIS THROUGH IN-SYSTEM PROGRAMMING**
 - Superior Quality of Results
 - Tightly Integrated with Leading CAE Vendor Tools
 - Productivity Enhancing Timing Analyzer, Explore Tools, Timing Simulator and ispANALYZER[™]
 - PC and UNIX Platforms

Functional Block Diagram*



Description

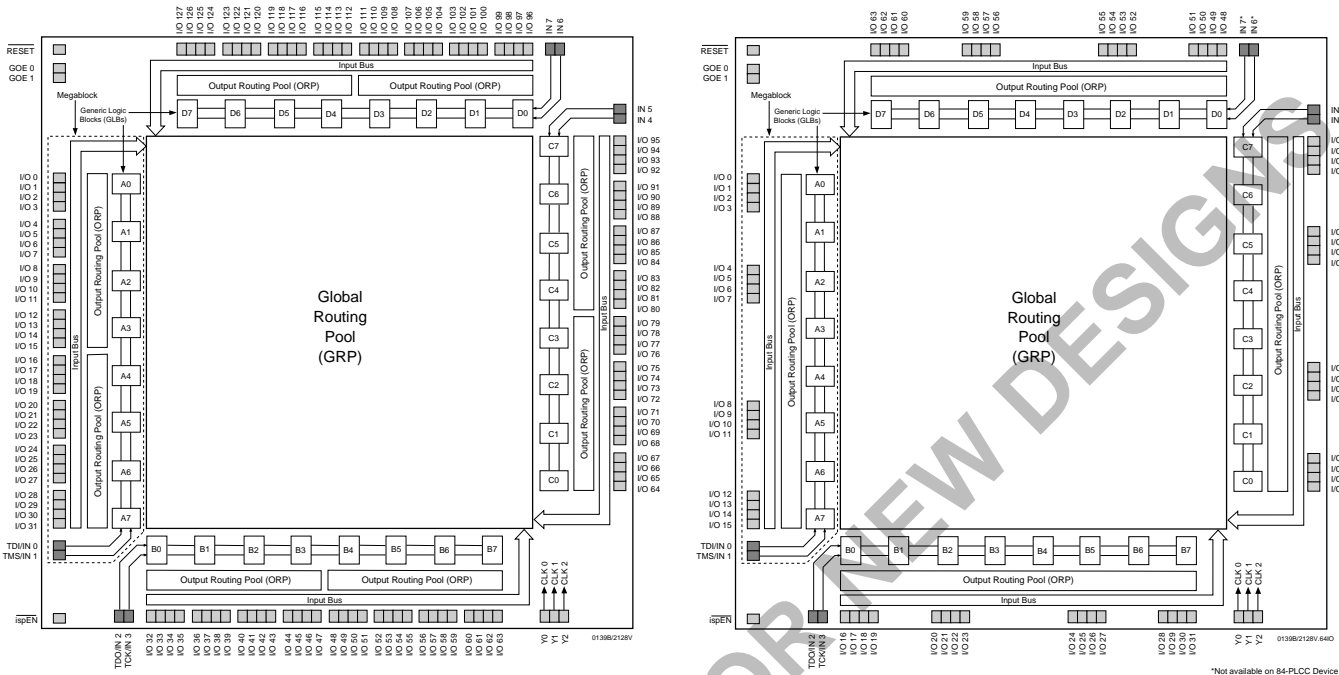
The ispLSI 2128V is a High Density Programmable Logic Device available in 128 and 64 I/O-pin versions. The device contains 128 Registers, eight Dedicated Input pins, three Dedicated Clock Input pins, two dedicated Global OE input pins and a Global Routing Pool (GRP). The GRP provides complete interconnectivity between all of these elements. The ispLSI 2128V features in-system programmability through the Boundary Scan Test Access Port (TAP). The ispLSI 2128V offers non-volatile reprogrammability of the logic, as well as the interconnect to provide truly reconfigurable systems.

The basic unit of logic on the ispLSI 2128V device is the Generic Logic Block (GLB). The GLBs are labeled A0, A1 .. D7 (see Figure 1). There are a total of 32 GLBs in the ispLSI 2128V device. Each GLB is made up of four macrocells. Each GLB has 18 inputs, a programmable AND/OR/Exclusive OR array, and four outputs which can be configured to be either combinatorial or registered. Inputs to the GLB come from the GRP and dedicated inputs. All of the GLB outputs are brought back into the GRP so that they can be connected to the inputs of any GLB on the device.

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Functional Block Diagram

Figure 1. ispLSI 2128V Functional Block Diagram (128-I/O and 64-I/O Versions)



The 128-I/O 2128V contains 128 I/O cells, while the 64-I/O version contains 64 I/O cells. Each I/O cell is directly connected to an I/O pin and can be individually programmed to be a combinatorial input, output or bi-directional I/O pin with 3-state control. The signal levels are TTL compatible voltages and the output drivers can source 4mA or sink 8mA. Each output can be programmed independently for fast or slow output slew rate to minimize overall output switching noise. Device pins can be safely driven to 5V signal levels to support mixed-voltage systems.

Eight GLBs, 32 or 16 I/O cells, two dedicated inputs and two or one ORPs are connected together to make a Megablock (see Figure 1). The outputs of the eight GLBs are connected to a set of 32 or 16 universal I/O cells by the two or one ORPs. Each ispLSI 2128V device contains four Megablocks.

The GRP has as its inputs, the outputs from all of the GLBs and all of the inputs from the bi-directional I/O cells. All of these signals are made available to the inputs of the GLBs. Delays through the GRP have been equalized to minimize timing skew.

Clocks in the ispLSI 2128V device are selected using the dedicated clock pins. Three dedicated clock pins (Y0, Y1,

Y2) or an asynchronous clock can be selected on a GLB basis. The asynchronous or Product Term clock can be generated in any GLB for its own clock.

Programmable Open-Drain Outputs

In addition to the standard output configuration, the outputs of the ispLSI 2128V are individually programmable, either as a standard totem-pole output or an open-drain output. The totem-pole output drives the specified Voh and Vol levels, whereas the open-drain output drives only the specified Vol. The Voh level on the open-drain output depends on the external loading and pull-up. This output configuration is controlled by a programmable fuse. When this fuse is erased (JEDEC "1"), the output is configured as a totem-pole output. When this fuse is programmed (JEDEC "0"), the output is configured as an open-drain. The default configuration when the device is in bulk erased state is totem-pole configuration. The open-drain/totem-pole option is selectable through the ispDesignEXPERT software tools.

Absolute Maximum Ratings ¹

Supply Voltage V_{CC} -0.5 to +5.6V
 Input Voltage Applied -0.5 to +5.6V
 Off-State Output Voltage Applied -0.5 to +5.6V
 Storage Temperature -65 to 150°C
 Case Temp. with Power Applied -55 to 125°C
 Max. Junction Temp. (T_J) with Power Applied ... 150°C

1. Stresses above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or at any other conditions above those indicated in the operational sections of this specification is not implied (while programming, follow the programming specifications).

DC Recommended Operating Condition

| SYMBOL | PARAMETER | MIN. | MAX. | UNITS | |
|----------|--------------------|---|------|-------|---|
| V_{CC} | Supply Voltage | Commercial $T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$ | 3.0 | 3.6 | V |
| | | Industrial $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ | 3.0 | 3.6 | V |
| V_{IL} | Input Low Voltage | $V_{SS} - 0.5$ | 0.8 | V | |
| V_{IH} | Input High Voltage | 2.0 | 5.25 | V | |

Table 2-0005/2128V

Capacitance ($T_A=25^\circ\text{C}$, $f=1.0$ MHz)

| SYMBOL | PARAMETER | TYPICAL | UNITS | TEST CONDITIONS |
|--------|--|---------|-------|---|
| C_1 | Dedicated Input Capacitance | 10 | pf | $V_{CC} = 3.3\text{V}$, $V_{IN} = 2.0\text{V}$ |
| C_2 | I/O Capacitance | 10 | pf | $V_{CC} = 3.3\text{V}$, $V_{IO} = 2.0\text{V}$ |
| C_3 | Clock and Global Output Enable Capacitance | 15 | pf | $V_{CC} = 3.3\text{V}$, $V_Y = 2.0\text{V}$ |

Table 2-0006/2128V

Data Retention Specifications

| PARAMETER | MINIMUM | MAXIMUM | UNITS |
|-------------------------------|---------|---------|--------|
| Data Retention | 20 | – | Years |
| ispLSI Erase/Reprogram Cycles | 10000 | – | Cycles |

Table 2-0008/2128V

Switching Test Conditions

| | |
|--------------------------------|------------------|
| Input Pulse Levels | GND to 3.0V |
| Input Rise and Fall Time | ≤ 3ns 10% to 90% |
| Input Timing Reference Levels | 1.5V |
| Output Timing Reference Levels | 1.5V |
| Output Load | See Figure 2 |

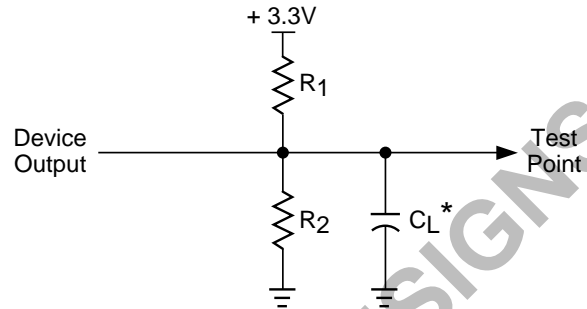
3-state levels are measured 0.5V from steady-state active level. Table 2 - 0003/2000

Output Load Conditions (see Figure 2)

| TEST CONDITION | | R1 | R2 | CL |
|----------------|-----------------------------------|------|------|------|
| A | | 316Ω | 348Ω | 35pF |
| B | Active High | ∞ | 348Ω | 35pF |
| | Active Low | 316Ω | 348Ω | 35pF |
| C | Active High to Z at $V_{OH}-0.5V$ | ∞ | 348Ω | 5pF |
| | Active Low to Z at $V_{OL}+0.5V$ | 316Ω | 348Ω | 5pF |

Table 2-0004/2128V

Figure 2. Test Load



*CL includes Test Fixture and Probe Capacitance.

0213A/2128V

DC Electrical Characteristics

Over Recommended Operating Conditions

| SYMBOL | PARAMETER | CONDITION | MIN. | TYP. ³ | MAX. | UNITS |
|--------------------------------------|-----------------------------------|---|------|-------------------|------|-------|
| V_{OL} | Output Low Voltage | $I_{OL} = 8 \text{ mA}$ | – | – | 0.4 | V |
| V_{OH} | Output High Voltage | $I_{OH} = -4 \text{ mA}$ | 2.4 | – | – | V |
| I_{IL} | Input or I/O Low Leakage Current | $0V \leq V_{IN} \leq V_{IL} \text{ (Max.)}$ | – | – | -10 | μA |
| I_{IH} | Input or I/O High Leakage Current | $(V_{CC} - 0.2)V \leq V_{IN} \leq V_{CC}$ | – | – | 10 | μA |
| | | $V_{CC} \leq V_{IN} \leq 5.25V$ | – | – | 50 | mA |
| I_{IL-isp} | ispEN Input Low Leakage Current | $0V \leq V_{IN} \leq V_{IL}$ | – | – | -150 | μA |
| I_{IL-PU} | I/O Active Pull-Up Current | $0V \leq V_{IN} \leq V_{IL}$ | – | – | -150 | μA |
| I_{OS}¹ | Output Short Circuit Current | $V_{CC} = 3.3V, V_{OUT} = 0.5V$ | – | – | -100 | mA |
| I_{CC}^{2, 4} | Operating Power Supply Current | $V_{IL} = 0.0V, V_{IH} = 3.0V$ $f_{CLOCK} = 1 \text{ MHz}$ | – | 195 | – | mA |

Table 2-0007/2128V

1. One output at a time for a maximum duration of one second. $V_{OUT} = 0.5V$ was selected to avoid test problems by tester ground degradation. Characterized but not 100% tested.
2. Measured using eight 16-bit counters.
3. Typical values are at $V_{CC} = 3.3V$ and $T_A = 25^\circ C$.
4. Maximum I_{CC} varies widely with specific device configuration and operating frequency. Refer to the Power Consumption section of this data sheet and Thermal Management section of the Lattice Semiconductor Data Book or CD-ROM to estimate maximum I_{CC} .

External Timing Parameters

Over Recommended Operating Conditions

| PARAMETER | TEST COND. ⁴ | # ² | DESCRIPTION ¹ | -80 | | -60 | | UNITS |
|---------------------------------|-------------------------|----------------|--|------|------|------|------|-------|
| | | | | MIN. | MAX. | MIN. | MAX. | |
| t _{pd1} | A | 1 | Data Propagation Delay, 4PT Bypass, ORP Bypass | - | 10.0 | - | 15.0 | ns |
| t _{pd2} | A | 2 | Data Propagation Delay | - | 15.0 | - | 20.0 | ns |
| f _{max} | A | 3 | Clock Frequency with Internal Feedback ³ | 80.0 | - | 61.7 | - | MHz |
| f _{max} (Ext.) | - | 4 | Clock Frequency with External Feedback ($\frac{1}{t_{su2} + t_{co1}}$) | 64.5 | - | 51.3 | - | MHz |
| f _{max} (Tog.) | - | 5 | Clock Frequency, Max. Toggle | 100 | - | 71.4 | - | MHz |
| t _{su1} | - | 6 | GLB Reg. Setup Time before Clock, 4 PT Bypass | 7.0 | - | 9.0 | - | ns |
| t _{co1} | A | 7 | GLB Reg. Clock to Output Delay, ORP Bypass | - | 6.5 | - | 8.5 | ns |
| t _{h1} | - | 8 | GLB Reg. Hold Time after Clock, 4 PT Bypass | 0.0 | - | 0.0 | - | ns |
| t _{su2} | - | 9 | GLB Reg. Setup Time before Clock | 9.0 | - | 11.0 | - | ns |
| t _{co2} | - | 10 | GLB Reg. Clock to Output Delay | - | 7.5 | - | 9.5 | ns |
| t _{h2} | - | 11 | GLB Reg. Hold Time after Clock | 0.0 | - | 0.0 | - | ns |
| t _{r1} | A | 12 | Ext. Reset Pin to Output Delay | - | 14.0 | - | 16.0 | ns |
| t _{rw1} | - | 13 | Ext. Reset Pulse Duration | 7.0 | - | 8.0 | - | ns |
| t _{pto_{een}} | B | 14 | Input to Output Enable | - | 15.0 | - | 18.0 | ns |
| t _{pto_{edis}} | C | 15 | Input to Output Disable | - | 15.0 | - | 18.0 | ns |
| t _{go_{een}} | B | 16 | Global OE Output Enable | - | 10.0 | - | 12.0 | ns |
| t _{go_{edis}} | C | 17 | Global OE Output Disable | - | 10.0 | - | 12.0 | ns |
| t _{wh} | - | 18 | External Synchronous Clock Pulse Duration, High | 5.0 | - | 7.0 | - | ns |
| t _{wl} | - | 19 | External Synchronous Clock Pulse Duration, Low | 5.0 | - | 7.0 | - | ns |

Table 2-0030/2128V

1. Unless noted otherwise, all parameters use the GRP, 20 PTXOR path, ORP and Y0 clock.
2. Refer to Timing Model in this data sheet for further details.
3. Standard 16-bit counter using GRP feedback.
4. Reference Switching Test Conditions section.

Internal Timing Parameters¹

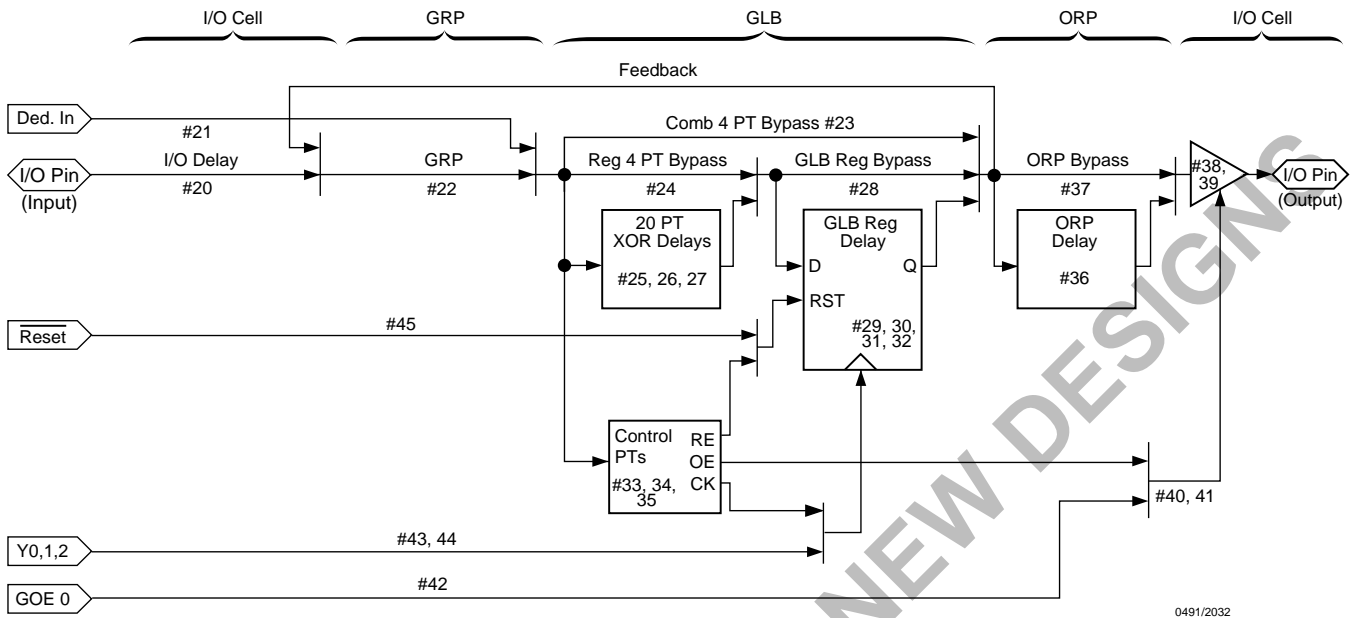
Over Recommended Operating Conditions

| PARAMETER | # ² | DESCRIPTION | -80 | | -60 | | UNITS |
|----------------------------|----------------|---|------|------|------|------|-------|
| | | | MIN. | MAX. | MIN. | MAX. | |
| Inputs | | | | | | | |
| t_{io} | 20 | Input Buffer Delay | – | 0.4 | – | 0.6 | ns |
| t_{din} | 21 | Dedicated Input Delay | – | 1.3 | – | 1.4 | ns |
| GRP | | | | | | | |
| t_{grp} | 22 | GRP Delay | – | 1.2 | – | 2.1 | ns |
| GLB | | | | | | | |
| t_{4ptbpc} | 23 | 4 Product Term Bypass Path Delay (Combinatorial) | – | 5.8 | – | 9.6 | ns |
| t_{4ptbpr} | 24 | 4 Product Term Bypass Path Delay (Registered) | – | 7.5 | – | 10.3 | ns |
| t_{1ptxor} | 25 | 1 Product Term/XOR Path Delay | – | 9.2 | – | 12.3 | ns |
| t_{20ptxor} | 26 | 20 Product Term/XOR Path Delay | – | 9.5 | – | 12.3 | ns |
| t_{xoradj} | 27 | XOR Adjacent Path Delay ³ | – | 11.3 | – | 14.4 | ns |
| t_{gbp} | 28 | GLB Register Bypass Delay | – | 0.3 | – | 1.3 | ns |
| t_{gsu} | 29 | GLB Register Setup Time before Clock | 0.2 | – | 0.2 | – | ns |
| t_{gh} | 30 | GLB Register Hold Time after Clock | 5.4 | – | 8.0 | – | ns |
| t_{gco} | 31 | GLB Register Clock to Output Delay | – | 1.6 | – | 1.6 | ns |
| t_{gro} | 32 | GLB Register Reset to Output Delay | – | 2.5 | – | 2.8 | ns |
| t_{ptre} | 33 | GLB Product Term Reset to Register Delay | – | 5.6 | – | 9.3 | ns |
| t_{ptoe} | 34 | GLB Product Term Output Enable to I/O Cell Delay | – | 8.5 | – | 10.4 | ns |
| t_{ptck} | 35 | GLB Product Term Clock Delay | 3.8 | 5.6 | 6.5 | 9.3 | ns |
| ORP | | | | | | | |
| t_{orp} | 36 | ORP Delay | – | 1.4 | – | 1.5 | ns |
| t_{orpbp} | 37 | ORP Bypass Delay | – | 0.4 | – | 0.5 | ns |
| Outputs | | | | | | | |
| t_{ob} | 38 | Output Buffer Delay | – | 2.2 | – | 2.2 | ns |
| t_{sl} | 39 | Output Slew Limited Delay Adder | – | 12.2 | – | 12.2 | ns |
| t_{oen} | 40 | I/O Cell OE to Output Enabled | – | 4.9 | – | 4.9 | ns |
| t_{odis} | 41 | I/O Cell OE to Output Disabled | – | 4.9 | – | 4.9 | ns |
| t_{goe} | 42 | Global Output Enable | – | 5.1 | – | 7.1 | ns |
| Clocks | | | | | | | |
| t_{gy0} | 43 | Clock Delay, Y0 to Global GLB Clock Line (Ref. clock) | 2.3 | 2.3 | 4.2 | 4.2 | ns |
| t_{gy1/2} | 44 | Clock Delay, Y1 or Y2 to Global GLB Clock Line | 2.3 | 2.3 | 4.2 | 4.2 | ns |
| Global Reset | | | | | | | |
| t_{gr} | 45 | Global Reset to GLB | – | 7.9 | – | 9.5 | ns |

1. Internal Timing Parameters are not tested and are for reference only.
2. Refer to Timing Model in this data sheet for further details.
3. The XOR adjacent path can only be used by hard macros.

Table 2-0036/2128V

ispLSI 2128V Timing Model



0491/2032

Derivations of tsu, th and tco from the Product Term Clock

$$\begin{aligned}
 \text{tsu} &= \text{Logic} + \text{Reg su} - \text{Clock (min)} \\
 &= (\mathbf{t_{io}} + \mathbf{t_{grp}} + \mathbf{t_{20ptxor}}) + (\mathbf{t_{gsu}}) - (\mathbf{t_{io}} + \mathbf{t_{grp}} + \mathbf{t_{ptck(min)}}) \\
 &= (\#20 + \#22 + \#26) + (\#29) - (\#20 + \#22 + \#35) \\
 5.9 \text{ ns} &= (0.4 + 1.2 + 9.5) + (0.2) - (0.4 + 1.2 + 3.8) \\
 \text{th} &= \text{Clock (max)} + \text{Reg h} - \text{Logic} \\
 &= (\mathbf{t_{io}} + \mathbf{t_{grp}} + \mathbf{t_{ptck(max)}}) + (\mathbf{t_{gh}}) - (\mathbf{t_{io}} + \mathbf{t_{grp}} + \mathbf{t_{20ptxor}}) \\
 &= (\#20 + \#22 + \#35) + (\#30) - (\#20 + \#22 + \#26) \\
 1.5 \text{ ns} &= (0.4 + 1.2 + 5.6) + (5.4) - (0.4 + 1.2 + 9.5) \\
 \text{tco} &= \text{Clock (max)} + \text{Reg co} + \text{Output} \\
 &= (\mathbf{t_{io}} + \mathbf{t_{grp}} + \mathbf{t_{ptck(max)}}) + (\mathbf{t_{gco}}) + (\mathbf{t_{orp}} + \mathbf{t_{ob}}) \\
 &= (\#20 + \#22 + \#35) + (\#31) + (\#36 + \#38) \\
 12.4 \text{ ns} &= (0.4 + 1.2 + 5.6) + (1.6) + (1.4 + 2.2)
 \end{aligned}$$

Note: Calculations are based upon timing specifications for the ispLSI 2128V-80L.

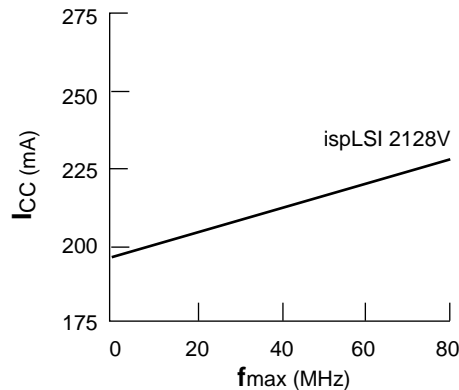
Table 2-0042/2128V

Power Consumption

Power consumption in the ispLSI 2128V device depends on two primary factors: the speed at which the device is operating and the number of Product Terms used.

Figure 3 shows the relationship between power and operating speed.

Figure 3. Typical Device Power Consumption vs fmax



Notes: Configuration of eight 16-bit counters
Typical current at 3.3V, 25° C

I_{CC} can be estimated for the ispLSI 2128V using the following equation:

$$I_{CC} \text{ (mA)} = 40 + (\# \text{ of PTs} * 0.6) + (\# \text{ of nets} * \text{Max freq} * 0.004)$$

Where:

- # of PTs = Number of Product Terms used in design
- # of nets = Number of Signals used in device
- Max freq = Highest Clock Frequency to the device (in MHz)

The I_{CC} estimate is based on typical conditions (V_{CC} = 3.3V, room temperature) and an assumption of two GLB loads on average exists. These values are for estimates only. Since the value of I_{CC} is sensitive to operating conditions and the program in the device, the actual I_{CC} should be verified.

0127/2128V

Power-up Considerations

When Lattice 3.3V 2000V devices are used in mixed 5V/3.3V applications, some consideration needs to be given to the power-up sequence. When the I/O pins on the 3.3V ispLSI devices are driven directly by 5V devices, a low impedance path can exist on the 3.3V device between its I/O and V_{cc} pins when the 3.3V supply is not present. This low impedance path can cause current to flow from the 5V device into the 3.3V ispLSI device. The maximum current occurs when the signals on the I/O pins are driven high by the 5V devices. If a large enough current flows through the 3.3V I/O pins, latch-up can occur and permanent device damage may result.

This latch-up condition occurs only during the power-up sequence when the 5V supply comes up before the 3.3V supply. The Lattice 3.3V ispLSI devices are guaranteed to withstand 5V interface signals within the device operating V_{cc} range of 3.0V to 3.6V.

The recommended power-up options are as follows:

Option 1: Ensure that the 3.3V supply is powered-up and stable before the 5V supply is powered up.

Option 2: Ensure that the 5V device outputs are driven to a high impedance or logic low state during power-up.

Pin Description

| NAME | 160-PIN PQFP PIN NUMBERS | 176-PIN TQFP PIN NUMBERS | DESCRIPTION |
|--|--|---|--|
| I/O 0 - I/O 4 I/O 5 - I/O 9 I/O 10 - I/O 14 I/O 15 - I/O 19 I/O 20 - I/O 24 I/O 25 - I/O 29 I/O 30 - I/O 34 I/O 35 - I/O 39 I/O 40 - I/O 44 I/O 45 - I/O 49 I/O 50 - I/O 54 I/O 55 - I/O 59 I/O 60 - I/O 64 I/O 65 - I/O 69 I/O 70 - I/O 74 I/O 75 - I/O 79 I/O 80 - I/O 84 I/O 85 - I/O 89 I/O 90 - I/O 94 I/O 95 - I/O 99 I/O 100 - I/O 104 I/O 105 - I/O 109 I/O 110 - I/O 114 I/O 115 - I/O 119 I/O 120 - I/O 124 I/O 125 - I/O 127 | 25, 26, 27, 28, 29, 30, 31, 32, 33, 34, 35, 36, 37, 38, 40, 41, 43, 44, 45, 46, 47, 48, 49, 50, 51, 52, 53, 54, 55, 56, 57, 58, 63, 64, 65, 66, 67, 68, 69, 70, 71, 72, 73, 74, 75, 76, 77, 78, 80, 81, 83, 84, 85, 86, 87, 88, 89, 90, 91, 92, 93, 94, 95, 96, 105, 106, 107, 108, 109, 110, 111, 112, 113, 114, 115, 116, 117, 118, 120, 121, 123, 124, 125, 126, 127, 128, 129, 130, 131, 132, 133, 134, 135, 136, 137, 138, 143, 144, 145, 146, 147, 148, 149, 150, 151, 152, 153, 154, 155, 156, 157, 158, 160, 1, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, 16 | 28, 29, 30, 31, 32, 33, 34, 35, 37, 38, 39, 40, 41, 42, 44, 45, 47, 48, 49, 50, 51, 52, 53, 54, 56, 57, 58, 59, 60, 61, 62, 63, 70, 71, 72, 73, 74, 75, 76, 77, 79, 80, 81, 82, 83, 84, 85, 86, 88, 89, 91, 92, 93, 94, 95, 96, 98, 99, 100, 101, 102, 103, 104, 105, 116, 117, 118, 119, 120, 121, 122, 123, 125, 126, 127, 128, 129, 130, 132, 133, 135, 136, 137, 138, 139, 140, 141, 142, 144, 145, 146, 147, 148, 149, 150, 151, 158, 159, 160, 161, 162, 163, 164, 165, 167, 168, 169, 170, 171, 172, 173, 174, 176, 1, 3, 4, 5, 6, 7, 8, 10, 11, 12, 13, 14, 15, 16, 17 | Input/Output Pins - These are the general purpose I/O pins used by the logic array. |
| IN 4 - IN 7 | 104, 141, 61, 17 | 114, 155, 67, 19 | Dedicated input pins to the device |
| GOE 0, GOE 1 | 100, 21 | 110, 23 | Global Output Enable input pins |
| RESET | 19 | 21 | Active Low (0) Reset pin which resets all the registers in the device. |
| Y0, Y1, Y2 | 18, 103, 98 | 20, 113, 108 | Dedicated Clock input. This clock input is connected to one of the clock inputs of all the GLBs in the device. |
| $\overline{\text{ispEN}}$ | 23 | 25 | Input Dedicated in-system programming Boundary Scan enable input pin. This pin is brought low to enable the programming mode. The TMS, TDI, TDO and TCK controls become active. |
| TDI/IN 0 | 24 | 26 | Input This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as a serial data input pin to load programming data into the device. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. |
| TCK/IN 3 | 97 | 107 | Input This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as a clock pin for the ISP/Boundary Scan state machine. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. |
| TMS/IN 1 | 60 | 66 | Input This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as a mode control pin for the ISP/Boundary Scan state machine. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. |
| TDO/IN 2 | 140 | 154 | Output/Input This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as an output pin to read serial shift register data. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. |
| GND | 22, 42, 62, 79, 99, 122, 139, 159 | 24, 46, 68, 87, 109, 134, 153, 175 | Ground (GND) |
| VCC | 2, 20, 39, 59, 82, 101, 119, 142 | 2, 22, 43, 65, 90, 111, 131, 156 | Vcc |
| NC ¹ | 102 | 9, 18, 27, 36, 55, 64, 69, 78, 97, 106, 112, 115, 124, 143, 152, 157, 166 | No Connect. |

1. NC pins are not to be connected to any active signal, VCC or GND.

Pin Description

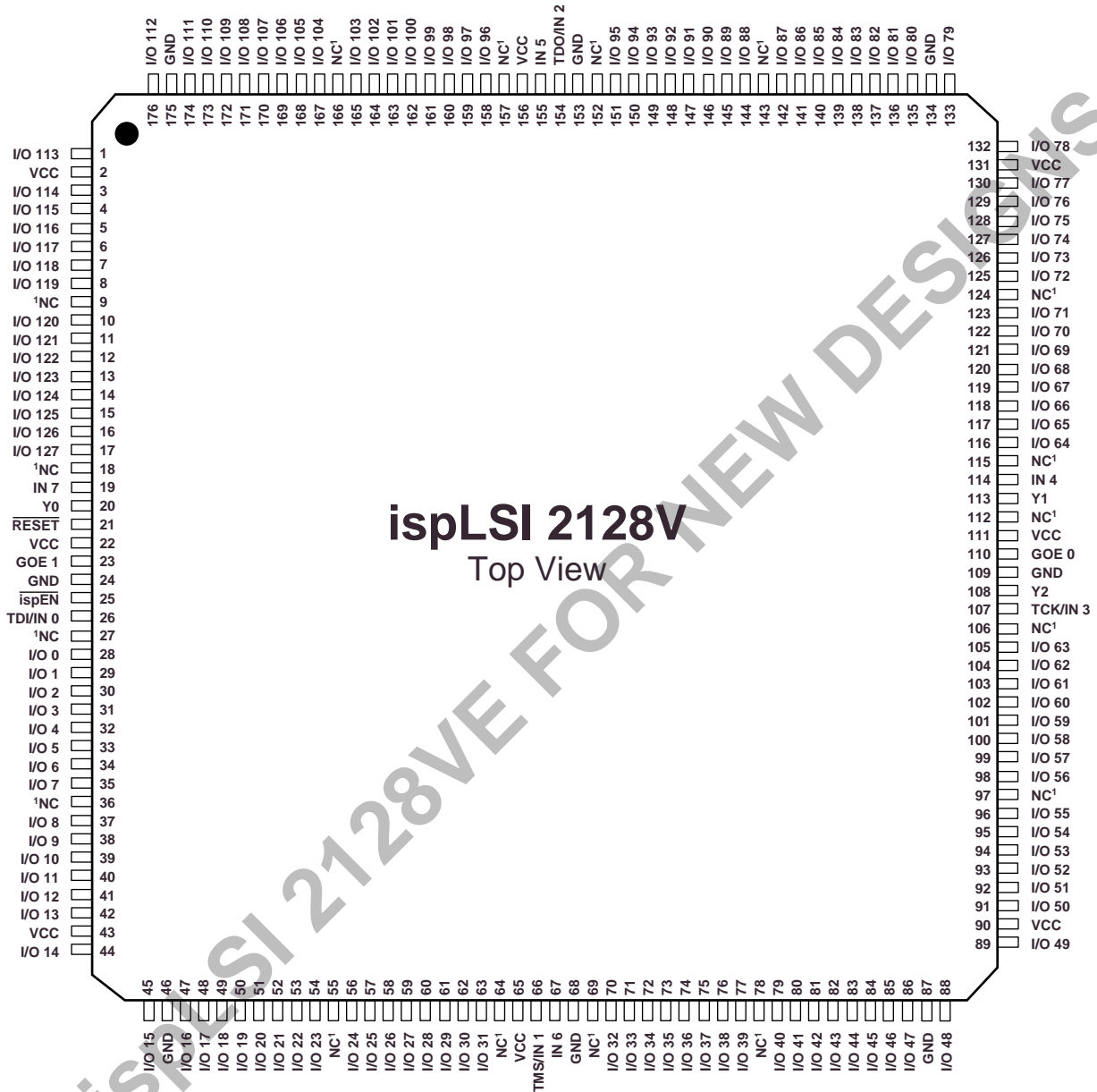
| NAME | 84-PIN PLCC PIN NUMBERS | 100-PIN TQFP PIN NUMBERS | DESCRIPTION |
|---|--|--|--|
| I/O 0 - I/O 3 I/O 4 - I/O 7 I/O 8 - I/O 11 I/O 12 - I/O 15 I/O 16 - I/O 19 I/O 20 - I/O 23 I/O 24 - I/O 27 I/O 28 - I/O 31 I/O 32 - I/O 35 I/O 36 - I/O 39 I/O 40 - I/O 43 I/O 44 - I/O 47 I/O 48 - I/O 51 I/O 52 - I/O 55 I/O 56 - I/O 59 I/O 60 - I/O 63 | 26, 27, 28, 29, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 40, 41, 45, 46, 47, 48, 49, 50, 51, 52, 53, 54, 55, 56, 57, 58, 59, 60, 68, 69, 70, 71, 72, 73, 74, 75, 76, 77, 78, 79, 80, 81, 82, 83, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, 16, 17, 18 | 17, 18, 19, 20, 22, 23, 24, 26, 27, 28, 29, 30, 32, 33, 34, 35, 40, 41, 42, 43, 45, 46, 47, 48, 49, 51, 52, 53, 55, 56, 57, 58, 67, 68, 69, 70, 72, 73, 74, 76, 77, 78, 79, 80, 82, 83, 84, 85, 90, 91, 92, 93, 95, 96, 97, 98, 99, 1, 2, 3, 5, 6, 7, 8 | Input/Output Pins - These are the general purpose I/O pins used by the logic array. |
| IN 4 - IN 7 | | 66, 88, 38, 9 | Dedicated input pins to the device |
| GOE 0, GOE 1 | 64, 22 | 62, 13 | Global Output Enable input pins |
| RESET Y0, Y1, Y2 | 20 19, 67, 62 | 11 10, 65, 60 | Active Low (0) Reset pin which resets all the registers in the device. Dedicated Clock input. This clock input is connected to one of the clock inputs of all the GLBs in the device. |
| ispEN | 24 | 15 | Input — Dedicated in-system programming Boundary Scan enable input pin. This pin is brought low to enable the programming mode. The TMS, TDI, TDO and TCK controls become active. |
| TDI/IN 0 | 25 | 16 | Input — This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as a serial data input pin to load programming data into the device. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. |
| TCK/IN 3 | 61 | 59 | Input — This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as a clock pin for the ISP/Boundary Scan state machine. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. |
| TMS/IN 1 | 43 | 37 | Input — This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as a mode control pin for the ISP/Boundary Scan state machine. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. |
| TDO/IN 2 | 1 | 87 | Output/Input — This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as an output pin to read serial shift register data. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. |
| GND | 23, 44, 63, 84 | 14, 39, 61, 86 | Ground (GND) |
| VCC | 2, 21, 42, 65 | 12, 36, 63, 89 | Vcc |
| NC ¹ | 66 | 4, 21, 25, 31, 44, 50, 54, 64, 71, 75, 81, 94, 100 | No Connect. |

1. NC pins are not to be connected to any active signal, VCC or GND.

Table 2-0002B/2128V

Pin Configuration

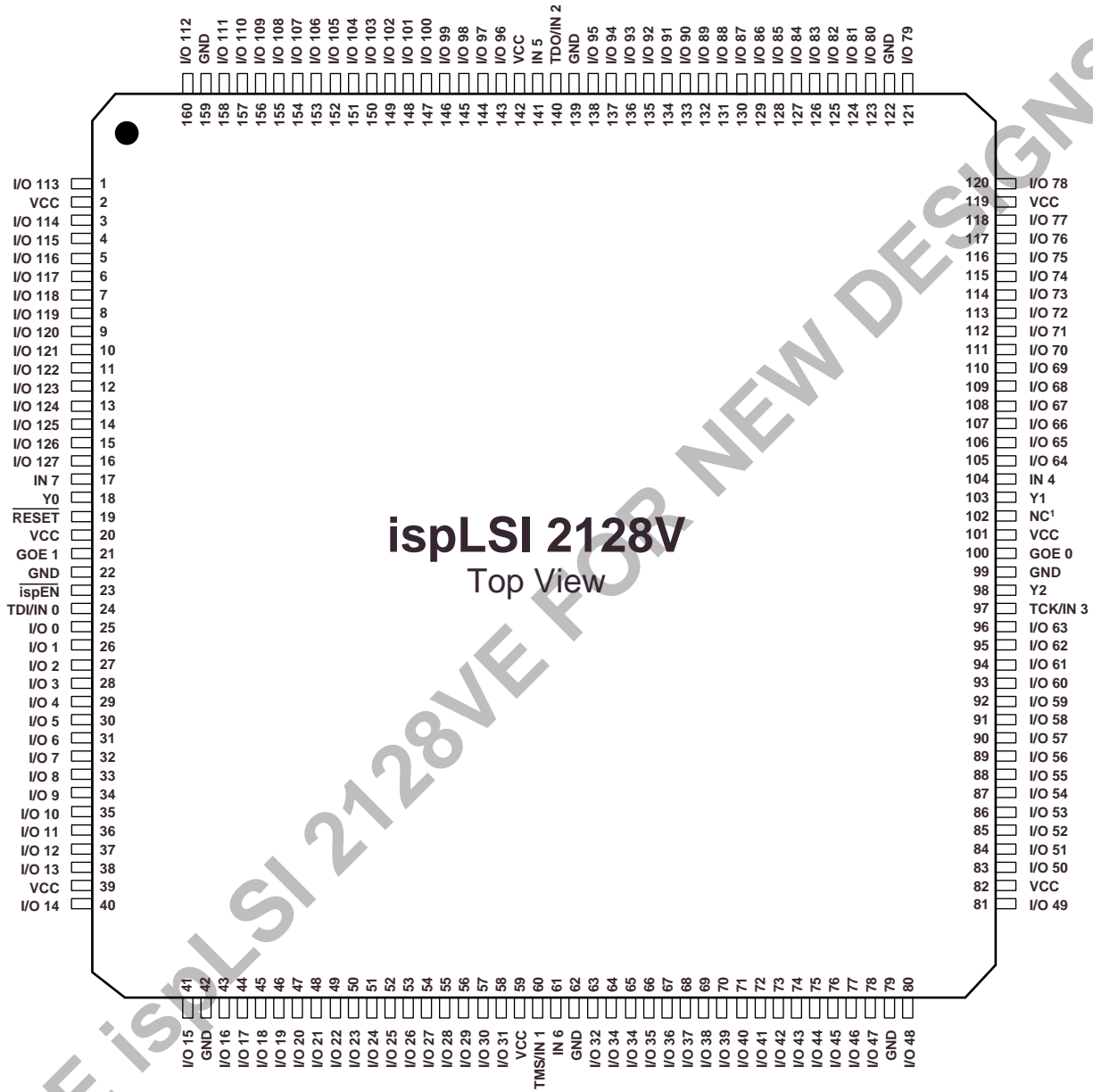
ispLSI 2128V 176-Pin TQFP Pinout Diagram



1. NC pins are not to be connected to any active signals, VCC or GND.

Pin Configuration

ispLSI 2128V 160-Pin PQFP Pinout Diagram

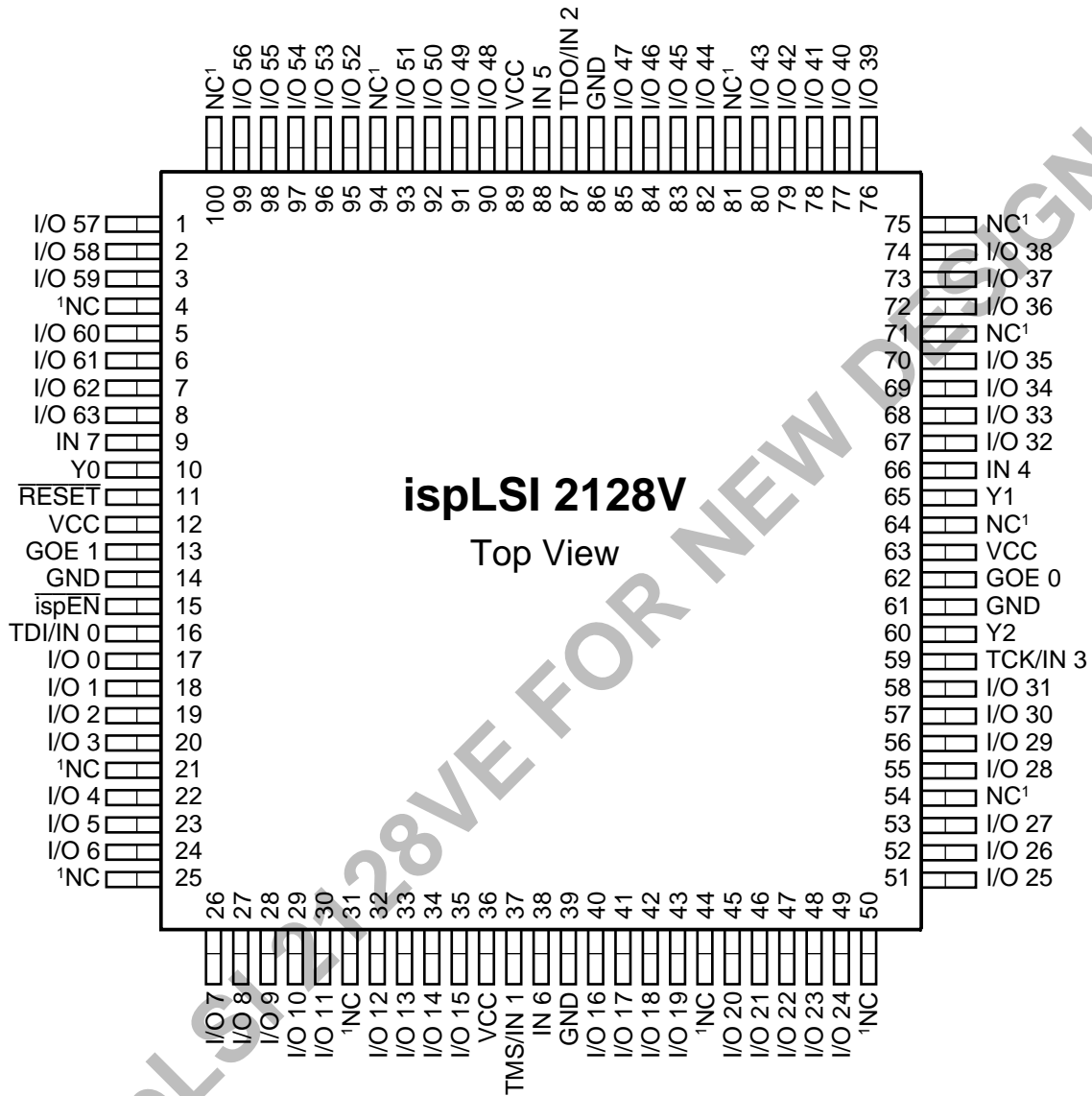


160-PQFP/2128LV

1. NC pins are not to be connected to any active signal, VCC or GND.

Pin Configuration

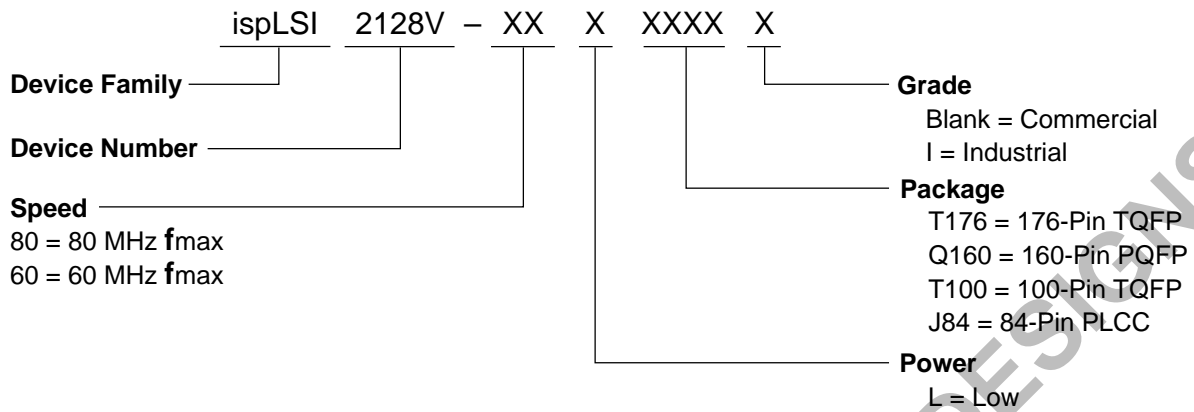
ispLSI 2128V 100-Pin TQFP Pinout Diagram



100-TQFP/2128V

1. NC pins are not to be connected to any active signals, VCC or GND.

Part Number Description



0212/2128V

ispLSI 2128V Ordering Information

COMMERCIAL

| FAMILY | f_{max} (MHz) | t_{pd} (ns) | I/Os | ORDERING NUMBER | PACKAGE |
|--------|-----------------|---------------|------|----------------------|--------------|
| ispLSI | 80 | 10 | 128 | ispLSI 2128V-80LT176 | 176-Pin TQFP |
| | 80 | 10 | 128 | ispLSI 2128V-80LQ160 | 160-Pin PQFP |
| | 80 | 10 | 64 | ispLSI 2128V-80LT100 | 100-Pin TQFP |
| | 80 | 10 | 64 | ispLSI 2128V-80LJ84 | 84-Pin PLCC |
| | 60 | 15 | 128 | ispLSI 2128V-60LT176 | 176-Pin TQFP |
| | 60 | 15 | 128 | ispLSI 2128V-60LQ160 | 160-Pin PQFP |
| | 60 | 15 | 64 | ispLSI 2128V-60LT100 | 100-Pin TQFP |
| | 60 | 15 | 64 | ispLSI 2128V-60LJ84 | 84-Pin PLCC |

*Contact factory for availability.

Table 2-0041A/2128V

INDUSTRIAL

| FAMILY | f_{max} (MHz) | t_{pd} (ns) | I/Os | ORDERING NUMBER | PACKAGE |
|--------|-----------------|---------------|------|-----------------------|--------------|
| ispLSI | 60 | 15 | 128 | ispLSI 2128V-60LT176I | 176-Pin TQFP |
| | 60 | 15 | 64 | ispLSI 2128V-60LT100I | 100-Pin TQFP |

Table 2-0041B/2128V